

**AMENDMENT TRANSMITTAL LETTER**Docket No.  
SON-1745Application No.  
09/512,336-Conf. #5387Filing Date  
February 24, 2000Examiner  
K. ChenArt Unit  
1765

Applicant(s): Seichi Fukuda

Invention: DRY ETCHING METHOD AND METHOD OF MANUFACTURING SEMICONDUCTOR APPARATUS

**TO THE COMMISSIONER FOR PATENTS**

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	4	- 20 =		x	0.00
Independent Claims	2	- 3 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
<b>TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:</b>					0.00

☒ Large Entity☐ Small Entity☒ No additional fee is required for this amendment.☐ Please charge Deposit Account No. \_\_\_\_\_ in the amount of \$ \_\_\_\_\_.  
A duplicate copy of this sheet is enclosed.☐ A check in the amount of \$ \_\_\_\_\_ to cover the filing fee is enclosed.☐ Payment by credit card. Form PTO-2038 is attached.☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. 18-0013 as described below. A duplicate copy of this sheet is enclosed.☒ Credit any overpayment.☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.Dated: May 14, 2003Ronald P. Kananen Reg. 24,104  
David K. Benson Reg. 42,314RADER, FISHMAN & GRAUER PLLC  
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Suite 501  
Washington, DC 20036  
(202) 955-3750RECEIVED  
MAY 15 2003  
TC 1700 MAIL ROOM



Docket No.: SON-1745  
(PATENT)

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5/15/03

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Seiichi Fukuda

Application No.: 09/512,336

Group Art Unit: 1765

Filed: February 24, 2000

Examiner: K. Chen

For: DRY ETCHING METHOD AND METHOD OF  
MANUFACTURING SEMICONDUCTOR  
APPARATUS

RECEIVED  
MAY 15 2003  
TC 1700 MAIL ROOM

**AMENDMENT**

**Box Non-Fee Amendment**

Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In response to the Office Action dated February 14, 2003 (Paper No. 21), please  
amend the above-identified U.S. patent application as follows: